

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
VISHNU K. AGARWAL et al.

Serial No.: 09/590,795

Filed: June 8, 2000

For: METHODS FOR FORMING AND
INTEGRATED CIRCUIT
STRUCTURES CONTAINING
RUTHENIUM AND TUNGSTEN
CONTAINING LAYERS

Confirmation No.: 9849

Group Art Unit: 2818

Examiner: David Vu

Atty. Dkt. No.: 2008.010100
(formerly 6047-53173)

Customer No.: 23720

**NOTICE OF APPEAL FROM THE PRIMARY EXAMINER
TO THE BOARD OF PATENT APPEALS AND INTERFERENCES**

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant hereby appeals to the Board of Patent Appeals and Interferences from the decision of the Primary Examiner mailed March 20, 2006, finally rejecting claims 1-15, 19, 30, 32, 33, 41, 42 and 66-70.

The Director is authorized to deduct the fee (\$500) for filing this Notice of Appeal and any other fees required under 37 C.F.R. §§ 1.16 to 1.21 from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/2008.010100.

Respectfully submitted,

WILLIAMS, MORGAN & AMERSON
CUSTOMER NO. 23720

Date: June 20, 2006

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